



Oxidation assisted crack growth in gas turbine materials

Micromechanical testing of thermally grown oxide layer in Allvac 718plus

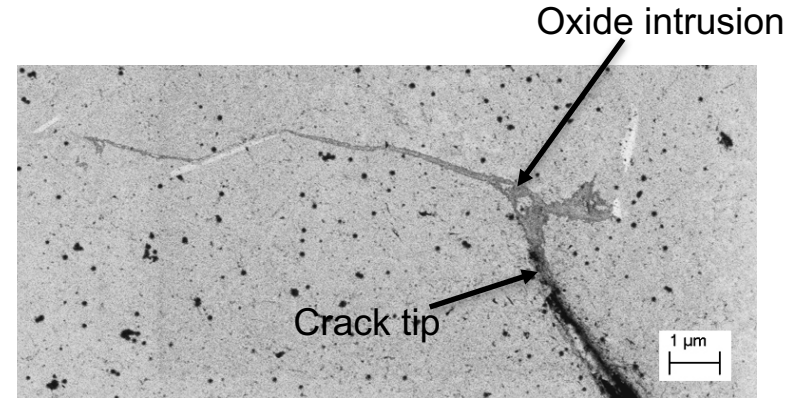
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OUTLINE

- Aim and motivation.
- Method development.
- Next steps.
- Summary.

Oxidation induced crack growth

- The original problem is the increased crack propagation rates during dwell-fatigue at high temperatures
- Several mechanisms proposed, but most recent evidence points towards stress assisted grain boundary oxidation (SAGBO), which involves fracture of oxide intrusion ahead of crack tip
- The major unknown in the most promising physically based model for the dwell-fatigue crack growth threshold is the fracture strain of the oxide (ϵ_f)
- **We want to develop methods to measure the fracture strain of grain boundary oxides in order to predict the threshold**



Step-by-step approach

Experimental characterization

1. Measuring fracture strength of surface oxides at **room temperature**
2. Measuring fracture strength of surface oxides at **elevated temperatures**
3. Measuring fracture strength of grain boundary oxides at **room temperature**
4. Measuring fracture strength of grain boundary oxides at **elevated temperatures**

Model development

1. Modelling of oxide fracture in bi-crystals
2. Modelling of oxide fracture in poly-crystals

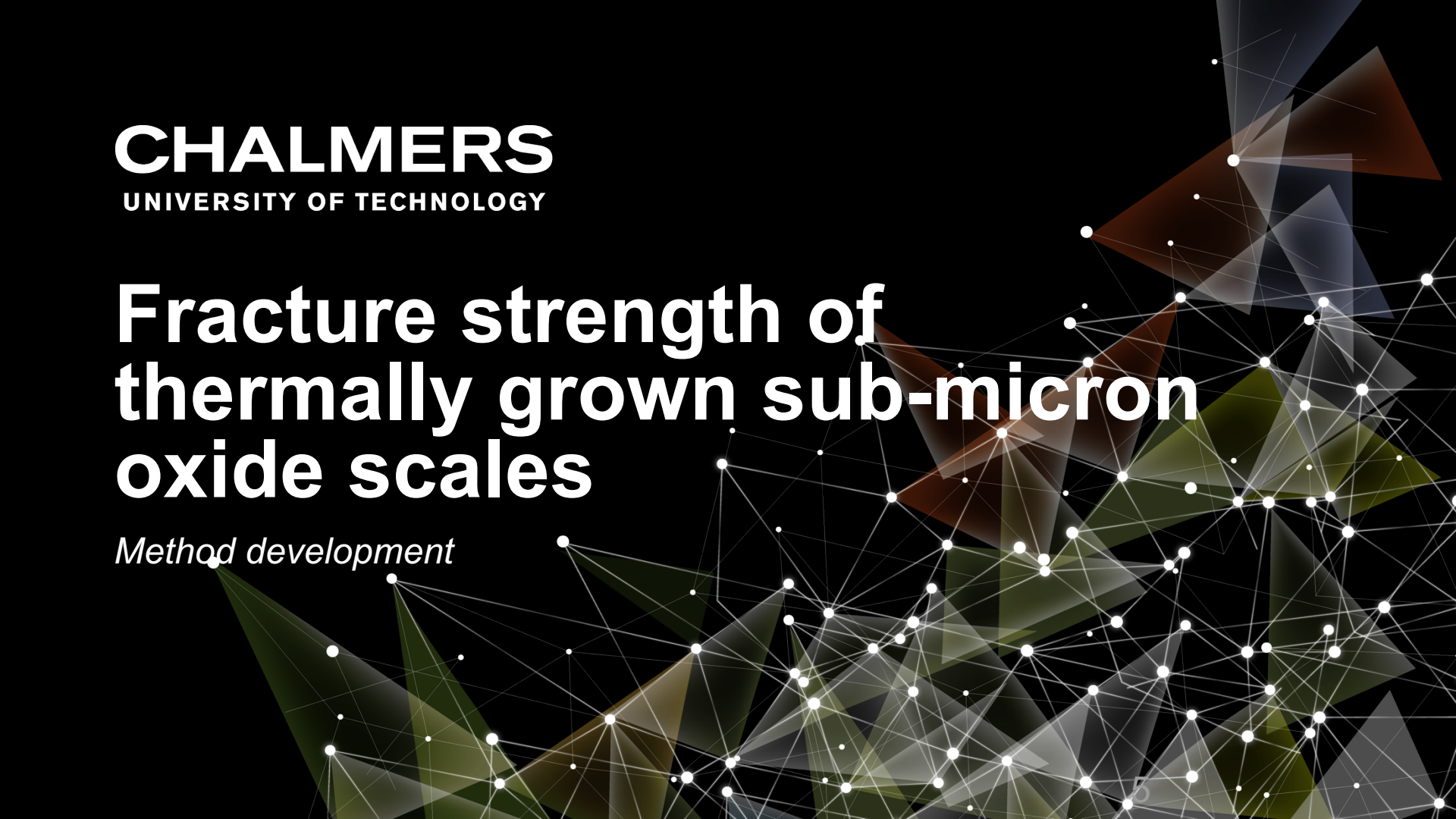
Ultimate goal

Coupling to oxidation models for simulating oxidation induced crack propagation in arbitrary poly-crystal microstructures

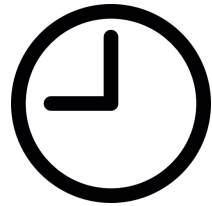


Fracture strength of thermally grown sub-micron oxide scales

Method development

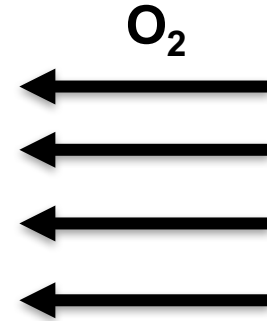
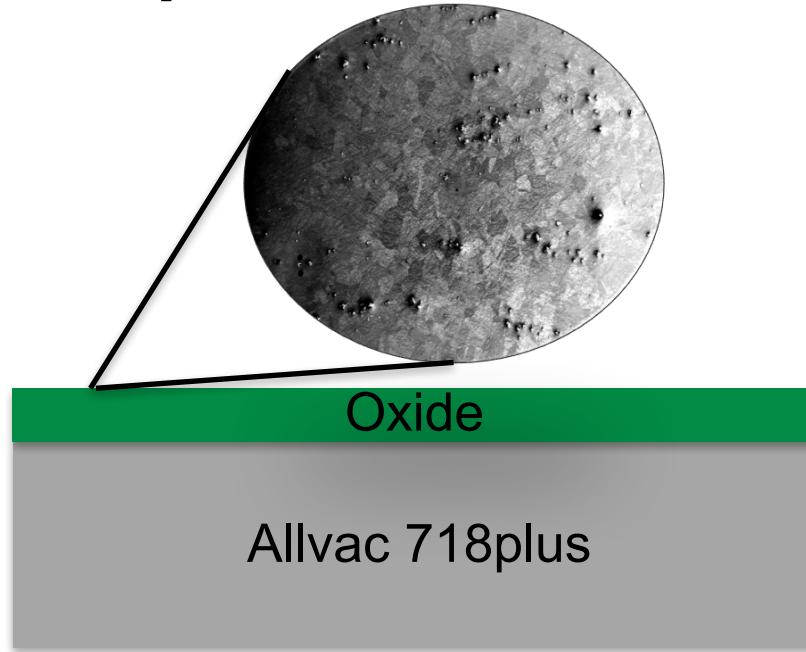
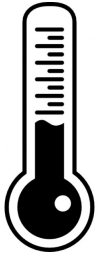


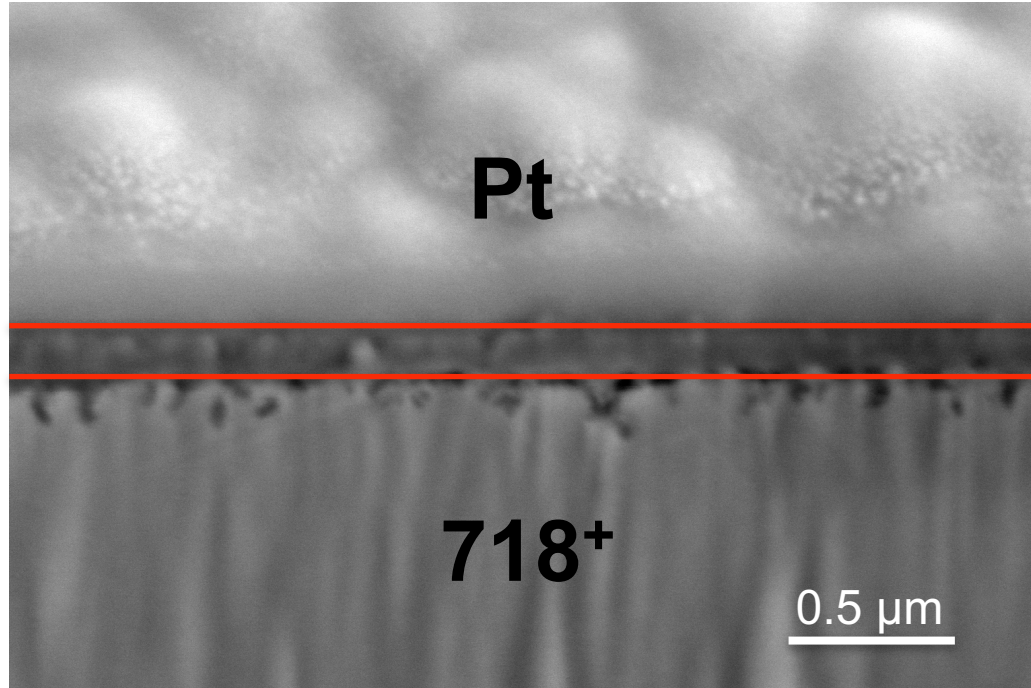
Thermally grown oxide – High temperature oxidation



100h,
500h

700 °C

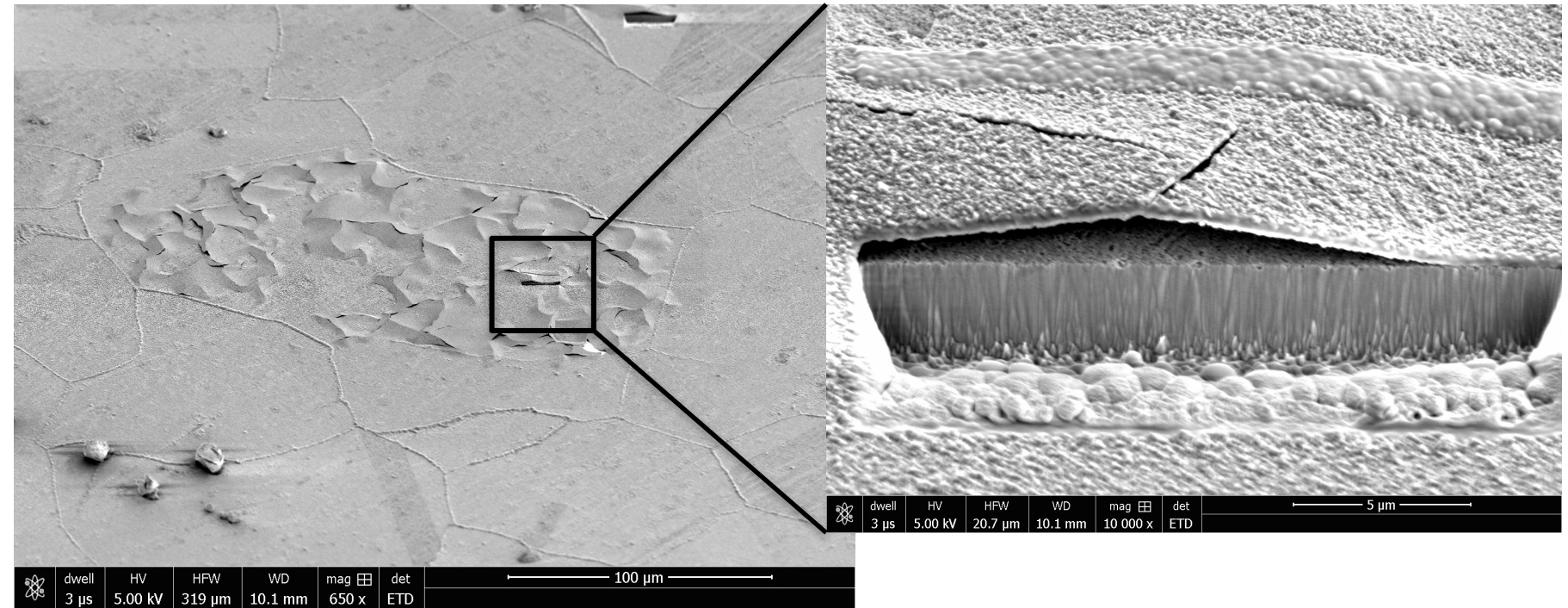




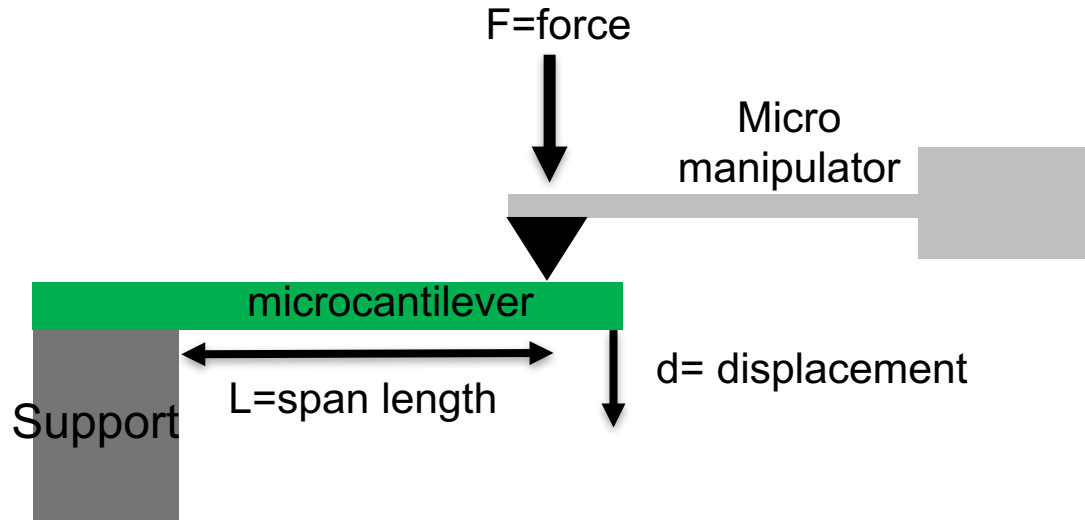
Oxide layer

- Cr rich oxide.
- ≈ 200 nm for 100h.
- ≈ 400 nm for 500h.

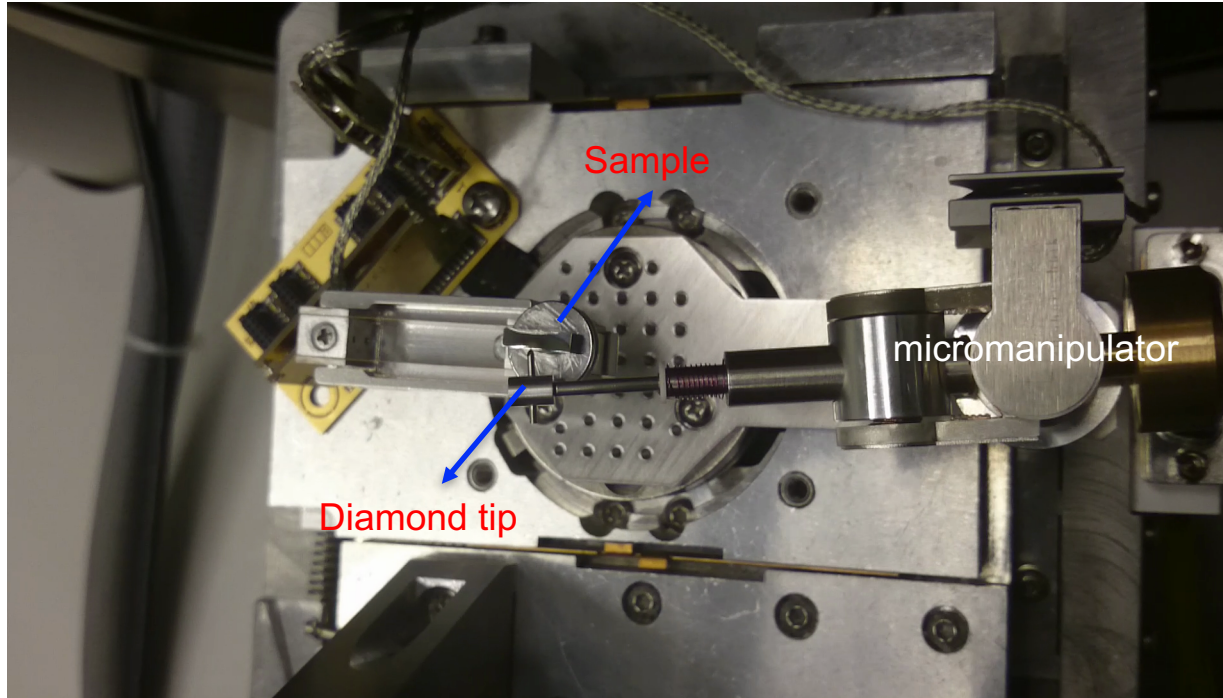
Poor adhesion of oxide (500h)



In-situ micromanipulator setup



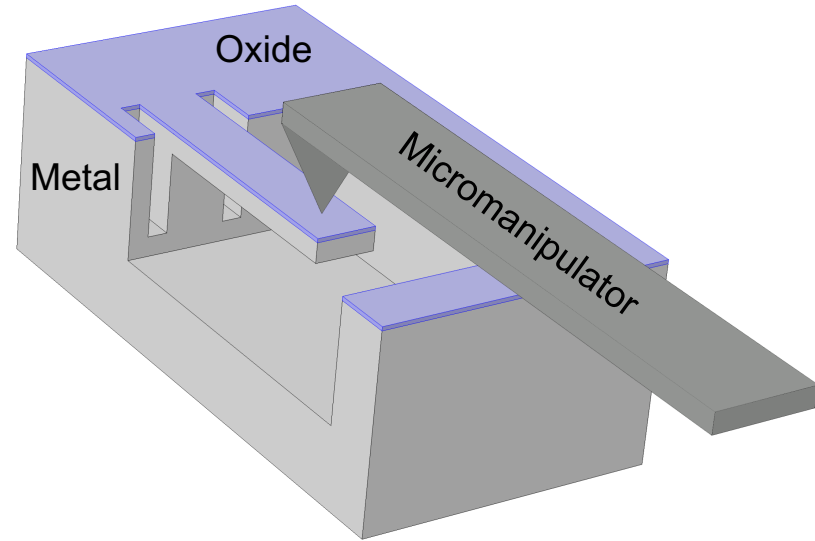
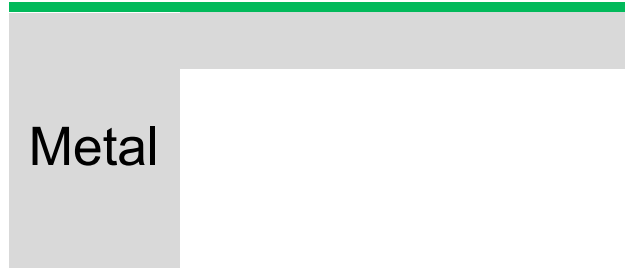
In-situ micromanipulator setup



Microcantilever type I

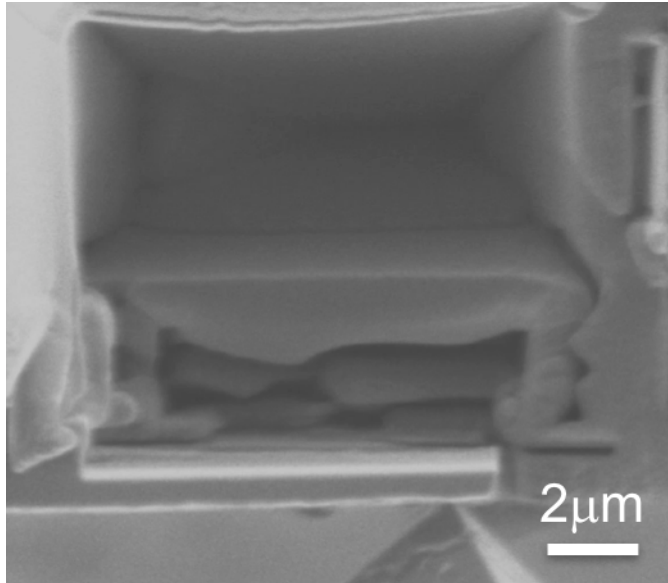
Oxide with base material

Oxide (~200nm)



Microcantilever type I

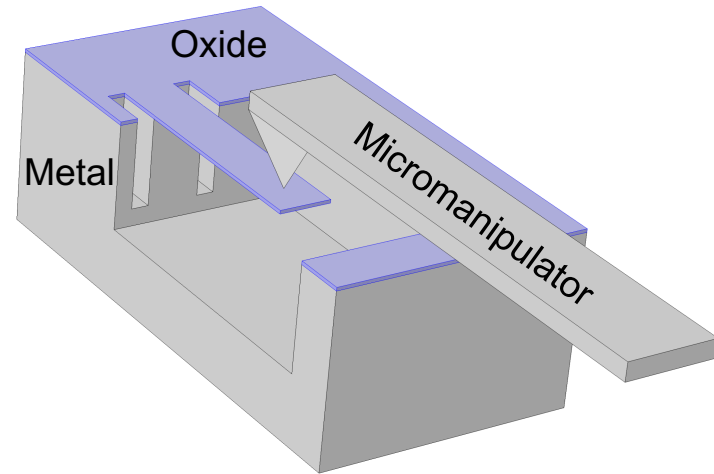
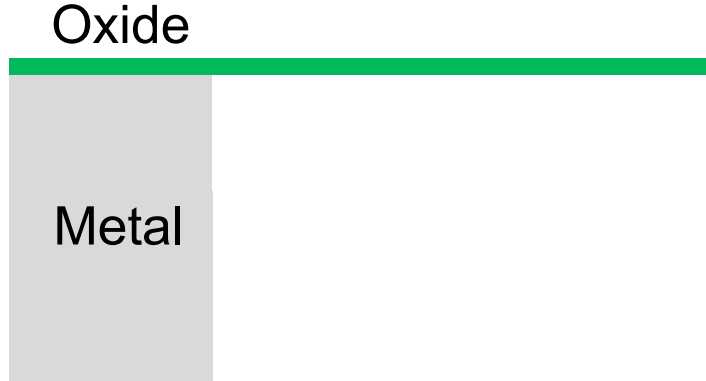
Oxide with base material

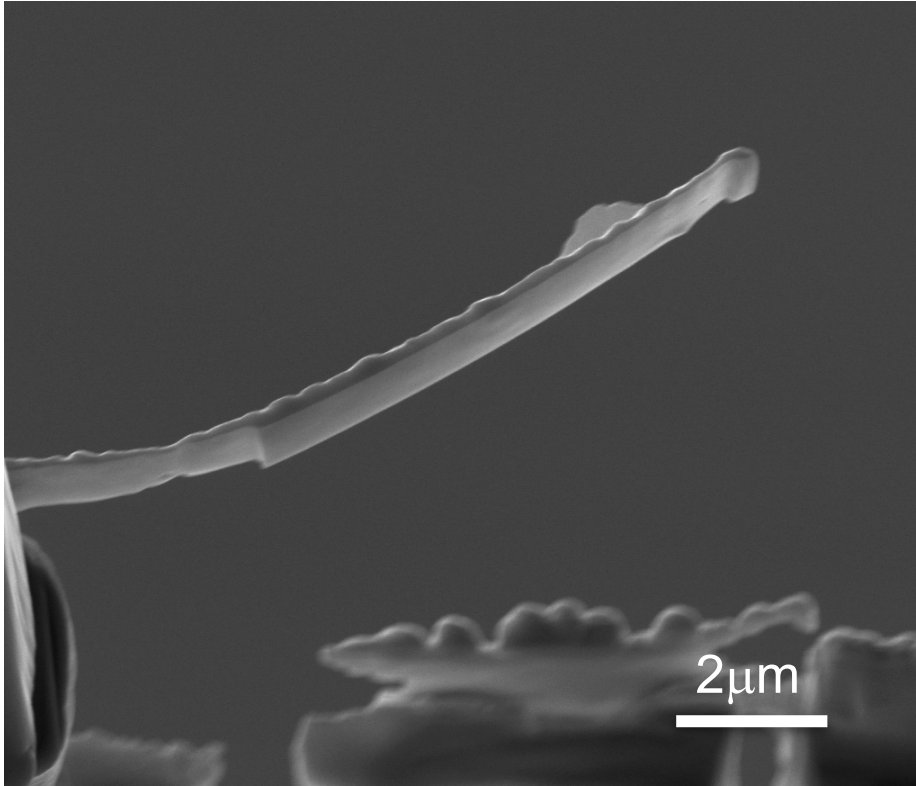


- First attempt with metal and oxide.
- To measure change in force and displacement during oxide fracture.
- Test on thin oxide.
- Oxide 200nm metal 800nm.
- No visible cracks on surface.

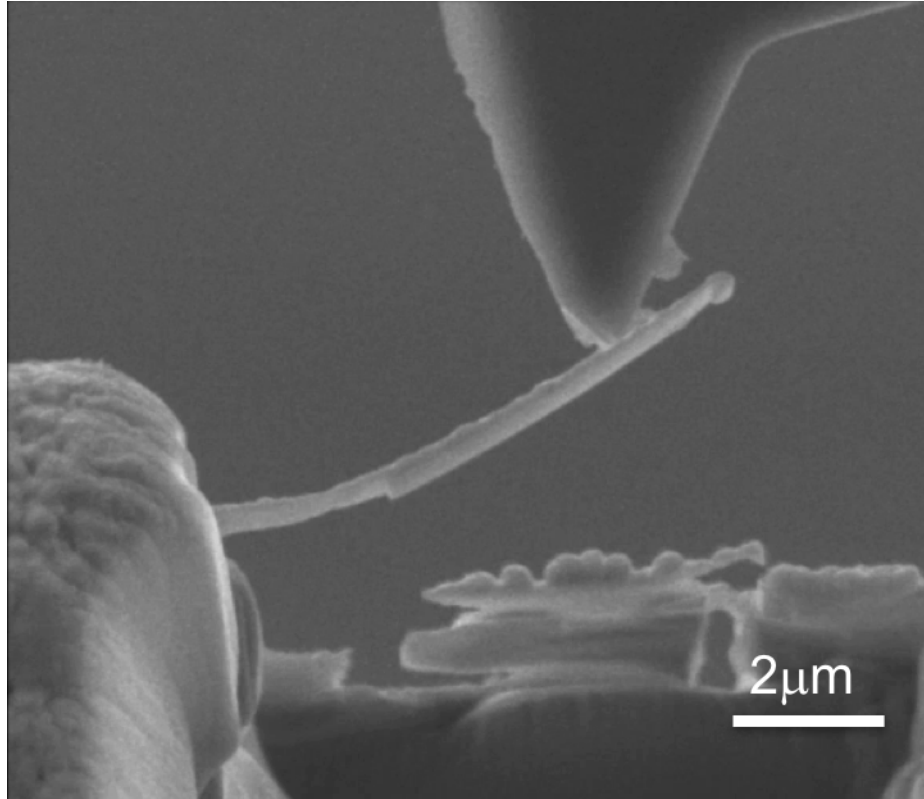
Microcantilever type II

Oxide cantilever – base material removed

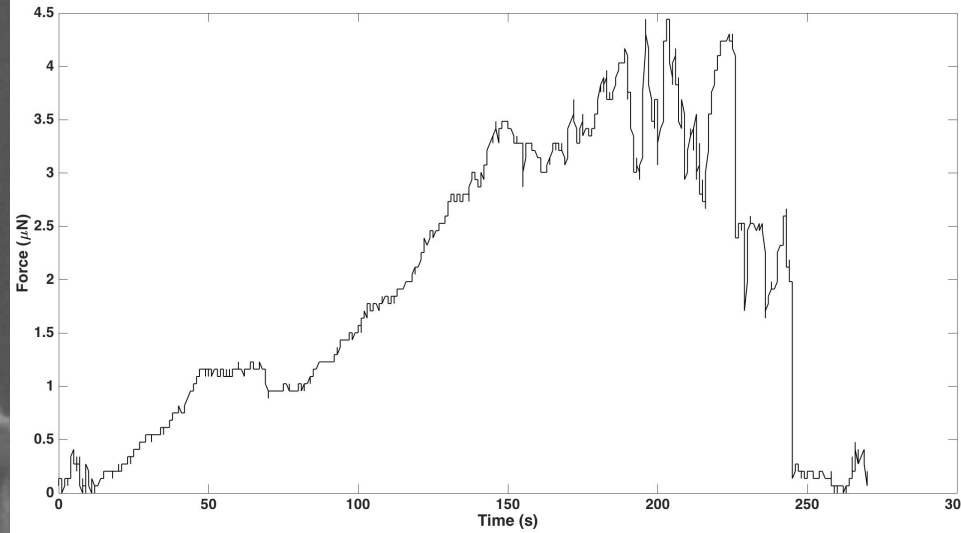




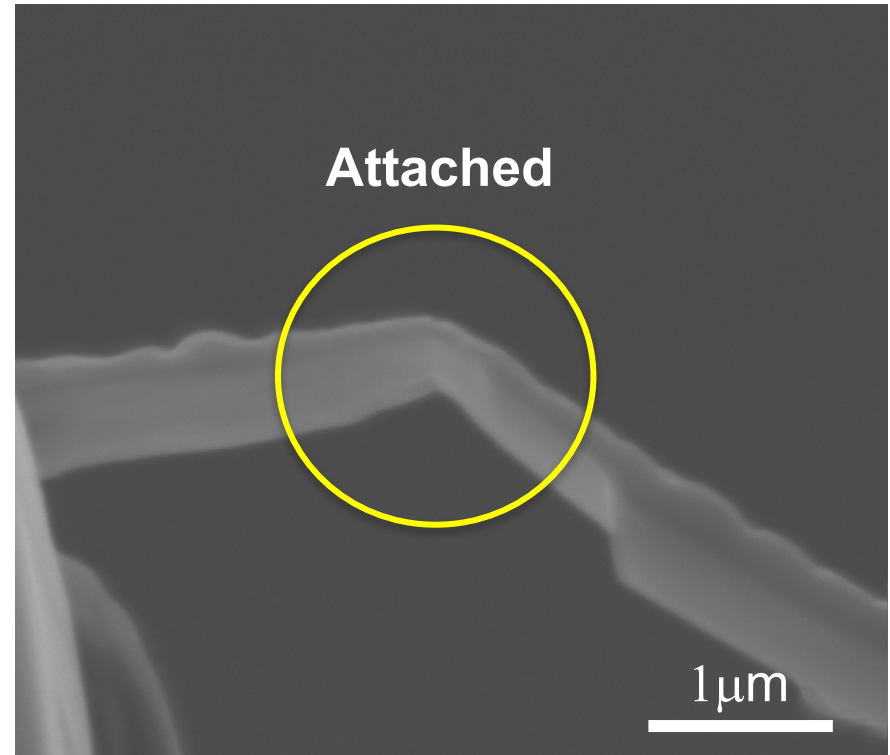
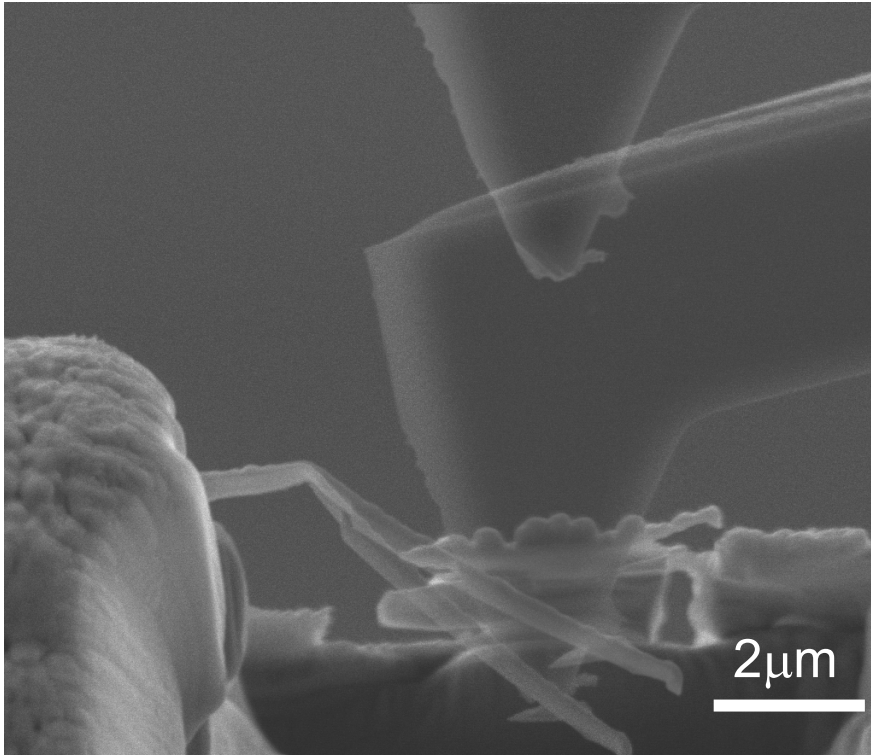
- Curvature due to residual stress.
- Can be used to estimate residual stress gradient.
- Bending during milling.
- Geometry not perfect.



Force vs time

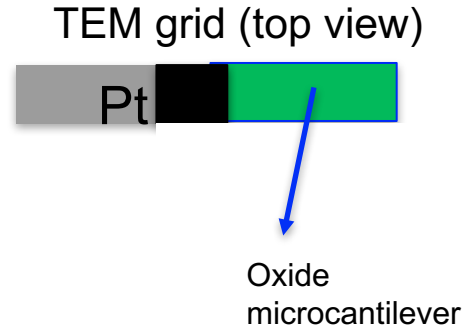
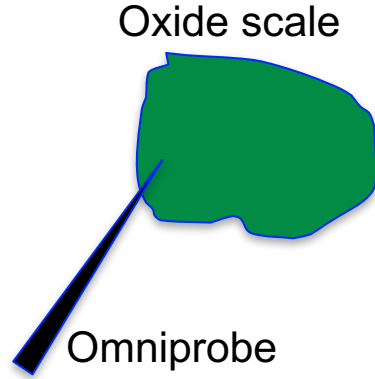


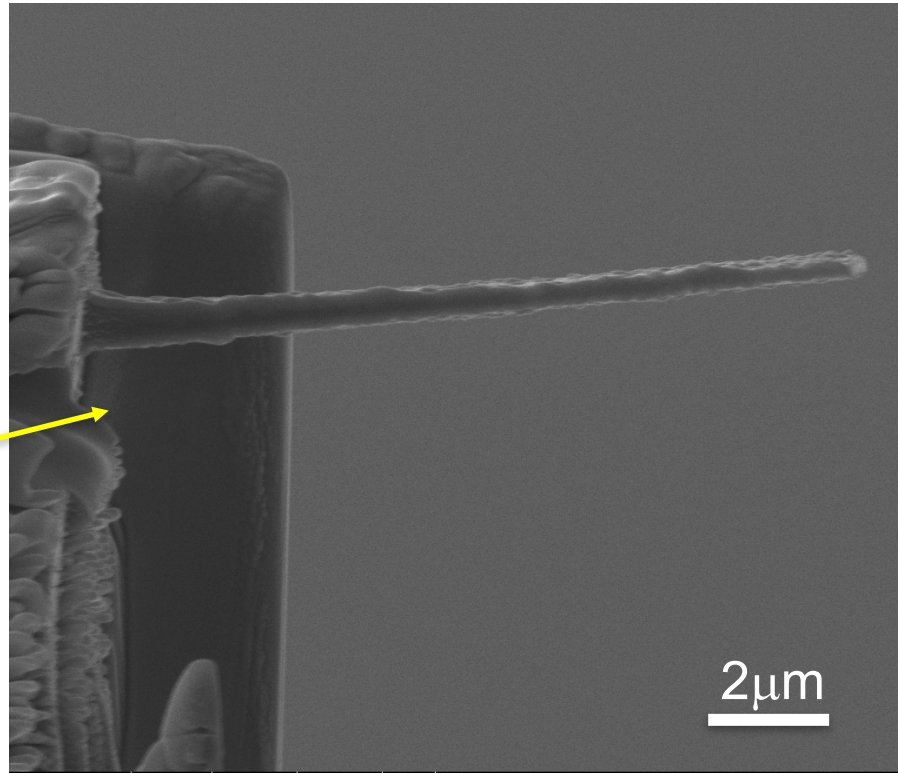
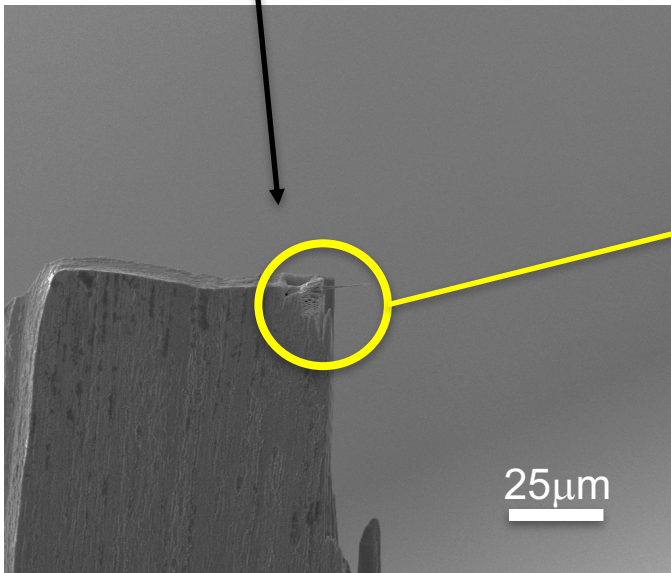
Recovery during unloading



Microcantilever type III

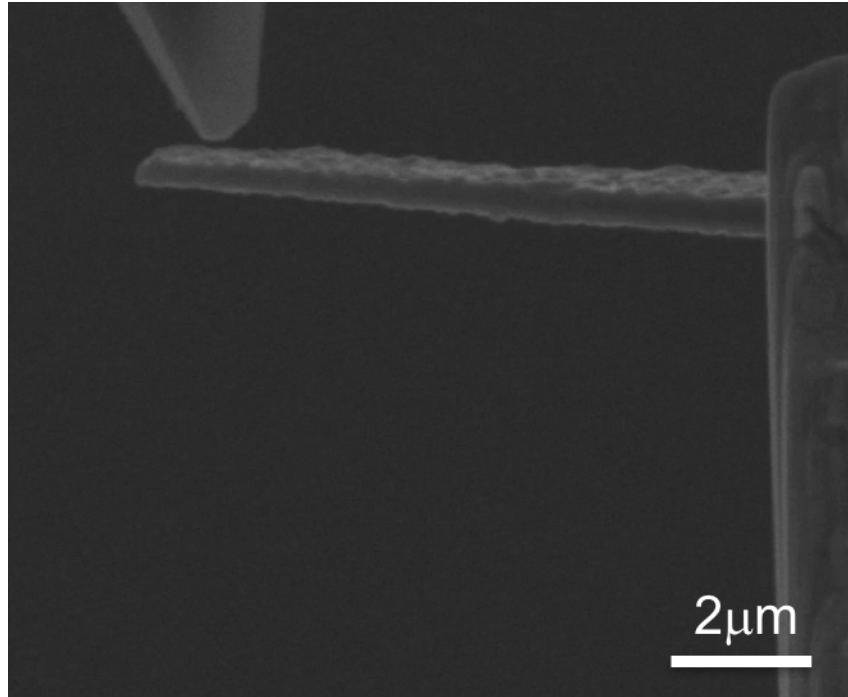
Oxide cantilever – peeled scale



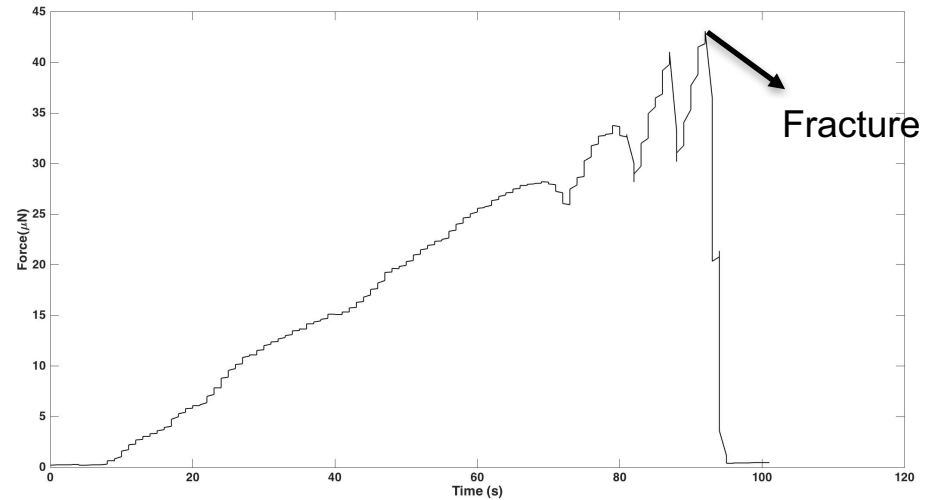


Microcantilever type III

Oxide cantilever – peeled scale



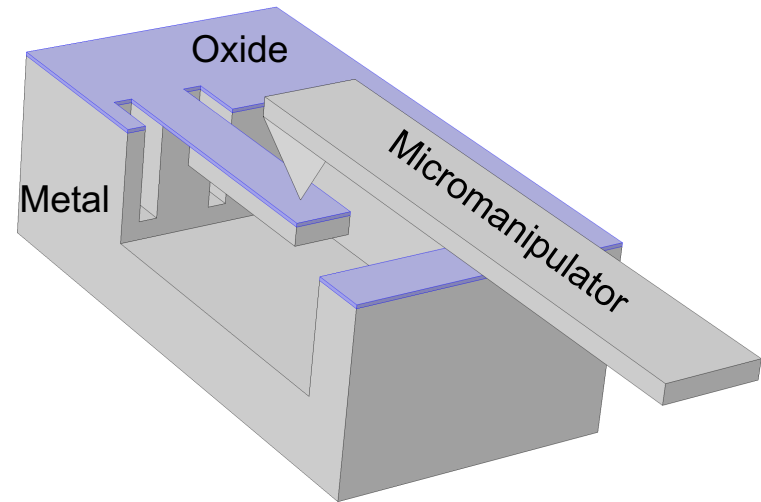
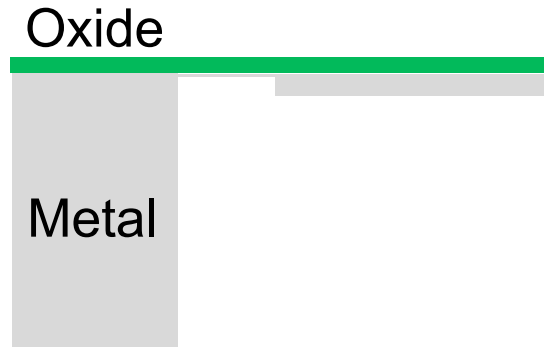
Force vs time

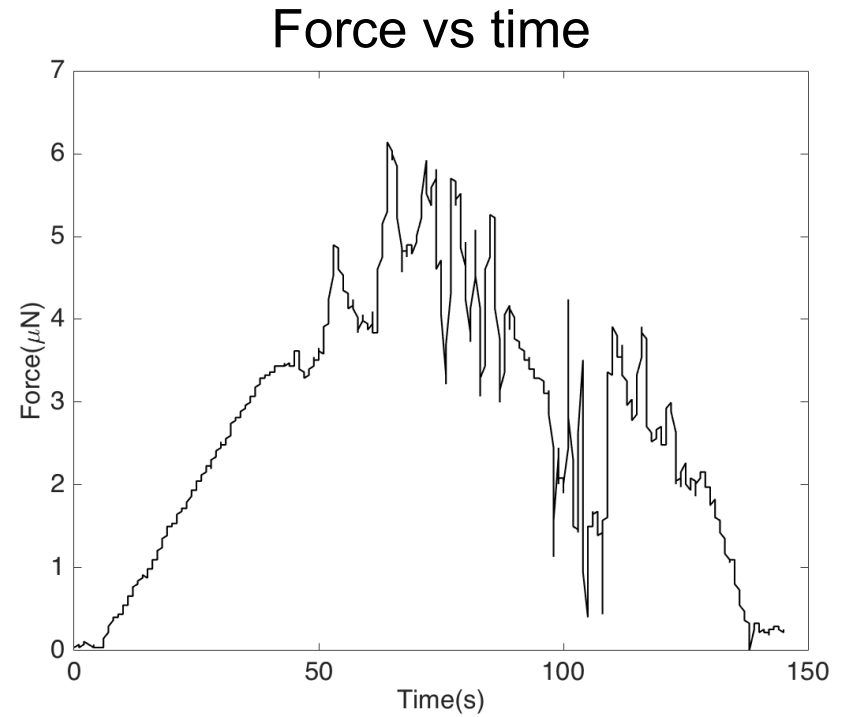
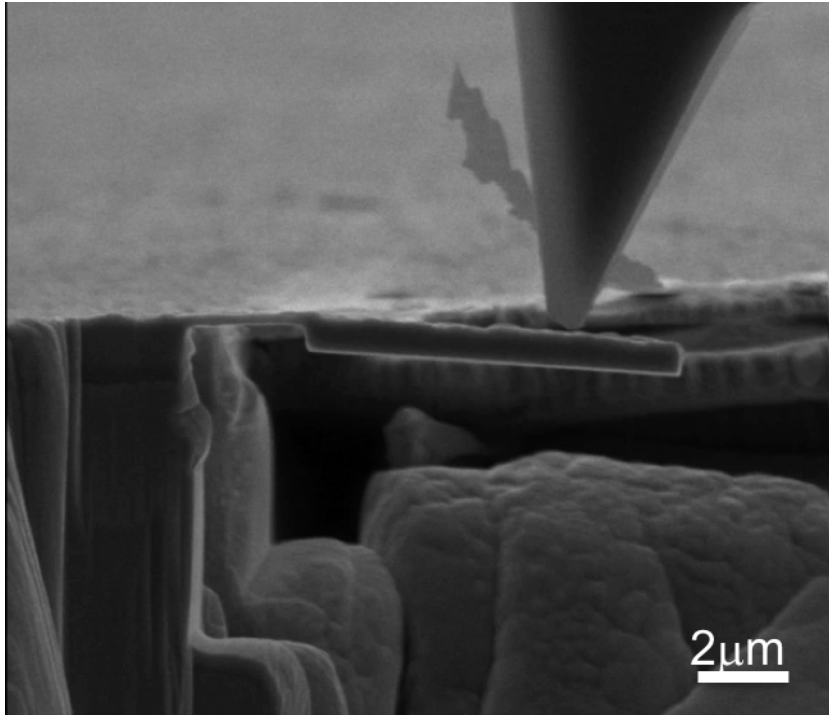


Concerns

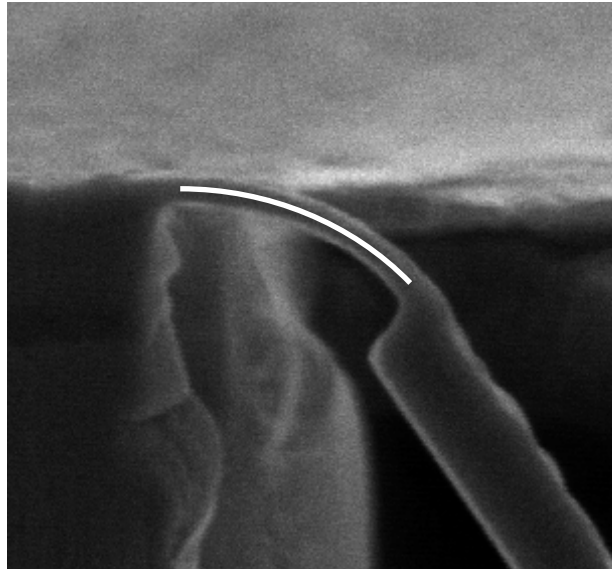
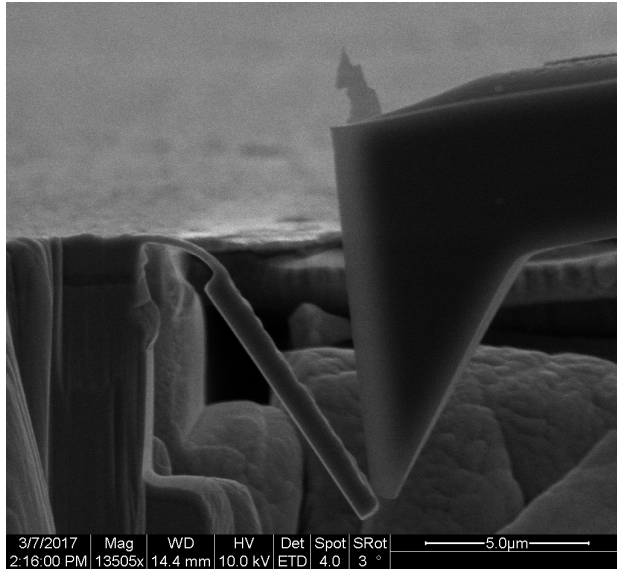
- Structural stability of platinum solder.
- High temperature strength of platinum.
- Geometry of cantilever.

Microcantilever Type IV





Strain and stress estimates



Rough approximation

$$\varepsilon = \frac{h}{2R} \approx 3.3 \%$$

$$\sigma = E\varepsilon \approx 9 \text{ GPa}$$

Next steps

- Detailed characterization of oxide layers (TEM/XRD).
- High temperature testing.
- Testing of pure Chromia (thermally grown, sintered).

Summary

- Testing of oxide microcantilevers to determine fracture properties is possible using current setup.
- Four different methods have been developed for testing.
- Some are more effective than the others.
- High temperature testing needs to be carried out for comparison of properties.
- Testing of pure chromia will be undertaken in order to study a simple system.



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